

TECHNICAL INFORMATION

SFY-330 heat sink is a white paste silicone product heavily filled with heat-conductive metal oxides. The incorporation of high efficient heat-conductive metal oxides promotes high thermal conductivity, low bleeding, and high-temperature stability. Up to approximately 175°C, the product is very stable to changes of temperature. It helps to maintain a positive heat sink seal that improves heat transfer from the electrical / electronic devices to the heat sink or chassis, thereby increasing overall efficiency of the devices.

Uses

SFY-330 heat sink is used to the base and mounting studs of transistors, diodes, and silicon-controlled rectifiers. It can also serve as a thermal coupler for many heat sink devices where efficient cooling is required. This product has also been applied as a high voltage corona-suppressant, non-flammable coating in connections for fly-back transformers in TV sets and similar applications.

Characteristics

Appearance	White Paste
Specific Gravity (25 °C, ASTM D 1475)	2.51
Consistency (Penetration, unworked)	180~240
Bleed after 24 hours at 200 °C (%)	0.05
Evaporation after 24 hours at 200 °C (%)	1.5
Drop Point (°C, ASTM D 2265)	300
Thermal Conductivity (W/mK, ASTM D 2214)	0.9
Dielectric Strength (volts/ mil, ASTM D 149)	200
Arc Resistance (sec, ASTM D 495)	160
Dielectric Constant (ASTM D 150)	100 Hz: 5 / 100 KHz: 5
Volume Resistivity (ohm-cm, ASTM D 1169)	2×10^{15}

The above data offered are based on our laboratory experiments for your references. The conditions of your use and application can affect the final results. Therefore it is imperative that you test our products, technical assistance and information to determine to your own satisfaction whether the product is suitable for your intended uses and applications.